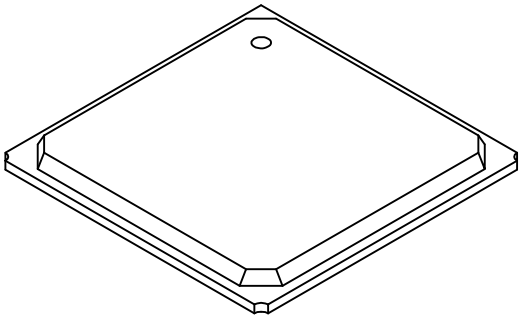
HMCCA,08/01/00,14:42:27,0Package,Version: Released11 DARNO,09/28/01,10:00:55,DCL27Q

REVISION HISTORY							
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GERBER FILE NAME	INCORPORATOR	DATE
00	C10605	INITIAL RELEASE	PGONZ	N/A	N/A	CCOAD	10/31/00
01	C13824	ADDED 240 AND 305 BALL MATRIX	DARNO	N/A	N/A	DARNO	09/28/01



8. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.
   C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A, VARIATION AAF-1 EXCEPT FOR b DIMENSION.

JEDEC(AMKOR) DIM	MIN	NOM	MAX
b	0.50(0.40)	0.60(0.50)	0.70(0.60)

7. A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK.
   AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 324.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 18 X 18.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL. X.X ±0.1 X.XX ±0.05 X.XXX ±0.030
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994
MATERIAL N/A
FINISH N/A
DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED PGONZ	10/23/00
CHECKED JMICK	10/23/00
PRODUCT MANAGER BGOGU	10/23/00
RELEASED RHOLM	10/31/00

Amkor Technology, Inc. Chandler, Arizona, USA
Anam Semiconductor, Inc., Seoul, Korea
Amkor Technology Philippines, Inc. Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE PACKAGE OUTLINE - PBGA CUSTOM, 18 X 18 MATRIX, 19.00mm X 19.00mm, 17.70mm X 17.70mm X 0.80mm MOLD CAP, 1.00mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE	SIO NUMBER	DWG NUMBER	REV
A3	N/A	81674	01

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	4:1	1 OF 4

FORM NO: MBFLAM101.DWG